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54FCT373 Octal Transparent Latch with TRI-STATE Outputs

National Semiconductor

54FCT373 Octal Transparent Latch with TRI-STATE[®] Outputs

General Description

Features

The 'FCT373 consists of eight latches with TRI-STATE outputs for bus organized system applications. The flip-flops appear transparent to the data when Latch Enable (LE) is HIGH. When LE is LOW, the data that meets the setup times is latched. Data appears on the bus when the Output Enable (\overline{OE}) is LOW. When \overline{OE} is HIGH the bus output is in the high impedance state.

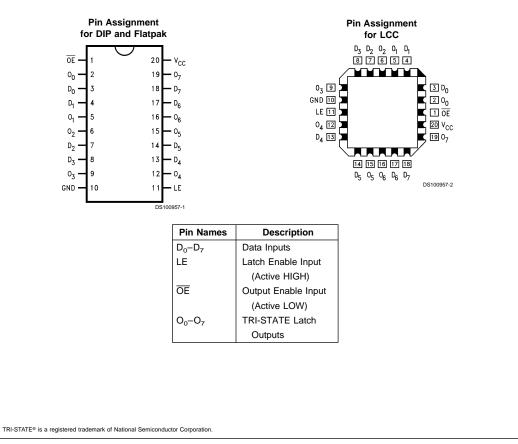
TRI-STATE outputs for bus interfacingTTL input and output level compatible

- TTL Input and output level cor
 CMOS newsr sensumption
- CMOS power consumption
- Output sink capability of 32 mA, source capability of 12 mA
- Standard Microcircuit Drawing (SMD) 5962-8764401

Ordering Code

Military	Package Number	Package Description		
54FCT373DMQB	J20A	20-Lead Ceramic Dual-In-Line		
54FCT373FMQB	W20A 20-Lead Cerpack			
54FCT373LMQB	E20A	E20A 20-Lead Ceramic Leadless Chip Carrier, Type C		

Connection Diagrams



Functional Description

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The 'FCT373 contains eight D-type latches with TRI-STATE output buffers. When the Latch Enable (LE) input is HIGH, data on the D_n inputs enters the latches. In this condition the latches are transparent, i.e., a latch output will change state each time its D input changes. When LE is LOW, the latches store the information that was present on the D inputs a setup time preceding the HIGH-to-LOW transition of LE. The TRI-STATE buffers are controlled by the Output Enable (\overline{OE}) input. When $\overline{\text{OE}}$ is LOW, the buffers are in the bi-state mode. When \overline{OE} is HIGH the buffers are in the high impedance mode but this does not interfere with entering new data into the latches.

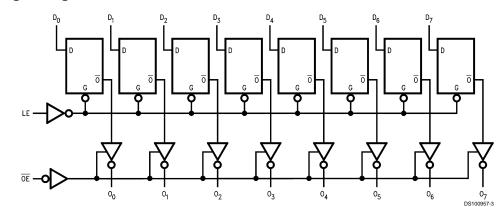
Logic Diagram

Truth Table

Inputs			Output	
LE	OE D _n		On	
Н	L	Н	н	
н	L	L	L	
L	L	Х	O _n (no change)	
Х	Н	Х	Z	

H = HIGH Voltage Level L = LOW Voltage Level X = Immaterial

Z = High Impedance State



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Storage Temperature	-65°C to +150°C
Ambient Temperature under Bias	-55°C to +125°C
Junction Temperature under Bias Ceramic	–55°C to +175°C
V _{CC} Pin Potential to Ground Pin	-0.5V to +7.0V
Input Voltage (Note 2)	-0.5V to +7.0V
Input Current (Note 2)	-30 mA to +5.0 mA
Voltage Applied to Any Output	
in the Disabled or	
Power-Off State	-0.5V to +5.5V

in the HIGH State Current Applied to Output in LOW State (Max) Over Voltage Latchup (I/O)

Recommended Operating Conditions

Free Air Ambient Temperature Military	–55°C to +125°C
Supply Voltage Military	+4.5V to +5.5V
Note 1: Absolute maximum ratings are values b be damaged or have its useful life impaired. Fund conditions is not implied.	

–0.5V to $V_{\rm CC}$

10V

twice the rated $I_{OL}\ (mA)$

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

DC Electrical Characteristics

Symbol	Parameter		FCT240		11-11-11-1	v	Conditions
			Min	Max	Units	V _{cc}	
V _{IH}	Input HIGH Voltage		2.0		V		Recognized HIGH Signal
VIL	Input LOW Voltage			0.8	V		Recognized LOW Signal
V _{CD}	Input Clamp Diode Voltage			-1.2	V	Min	I _{IN} = -18 mA
V _{OH} Output HIGH	54FCT	4.3		V	Min	I _{OH} = -300 uA	
	Voltage	54FCT	2.4		V	Min	I _{OH} = -12 mA
V _{OL}	Output LOW	54FCT		0.2	V	Min	I _{OL} = 300 μA
	Voltage	54FCT		0.5	V	Min	I _{OL} = 32 mA
I _{IH}	Input HIGH Current			5	μA	Max	V _{IN} = 5.5V
I _{IL}	Input LOW Current			-5	μA	Max	$V_{IN} = 0.0V$
I _{ozh}	High Impedance Output Current			10	μA	Max	V _{IN} = 5.5V
l _{ozl}	High Impedanc	e Output Current		-10	μA	Max	$V_{IN} = 0.0V$
l _{os}	Output Short-C	ircuit Current		-60	mA	Max	V _{OUT} = 0.0V
Iccq	Power Supply Current			1.5	mA	Max	$V_{IN} = 0.2V \text{ or } V_{IN} = 5.3V$
ΔI_{CC}	Power Supply	Current		2.0	mA	Max	V _{IN} = 3.4V
I _{CCT}				5.6	mA	Max	$ \begin{array}{l} V_{\text{IN}} = 3.4 \text{V or } V_{\text{IN}} = \text{GND}, \ \overline{\text{OE}} = \\ \text{GND}, \ f_{\text{I}} = 10 \text{Mhz}, \ \text{outputs open}, \\ \text{one bit toggling}, \ 50\% \ \text{duty cycle} \end{array} $
				4.0	mA	Max	$ \begin{array}{l} V_{\text{IN}} = 5.3 \text{V or } V_{\text{IN}} = 0.2 \text{V}, \overline{\text{OE}} = \\ \text{GND, } f_{\text{I}} = 10 \text{Mhz}, \text{ outputs open}, \\ \text{one bit toggling, 50\% duty cycle} \end{array} $
I _{CCD}	Dynamic I _{CC}			0.25	mA/MHz	Max	Outputs Open, \overline{OE} = GND, one bit toggling, 50% duty Cycle

Symbol	Parameter	54	FCT	Units	Fig. No.
		T _A = -55°(C to +125°C		
		$V_{\rm CC}$ = 4.5V to 5.5V C _L = 50 pF			
		Min	Max		
t _{PLH}	Propagation Delay	1.5	8.5	ns	Figure 4
t _{PHL}	D _n to O _n	1.5	8.5		
t _{PLH}	Propagation Delay	2.0	15.0	ns	Figure 4
t _{PHL}	LE to O _n	2.0	15.0		
t _{PZH}	Output Enable Time	1.5	13.5	ns	Figure 6
t _{PZL}		1.5	13.5		
t _{PHZ}	Output Disable Time	1.5	12.5	ns	Figure 6
t _{PLZ}		1.5	12.5		

AC Operating Requirements

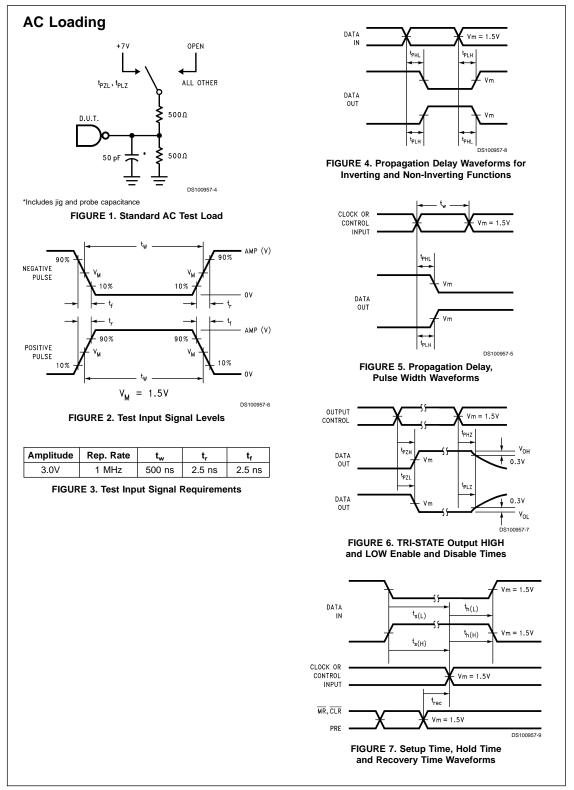
Symbol	Parameter	54	54FCT		Fig.
		$T_{A} = -55^{\circ}$	C to +125°C		No.
		$V_{CC} = 4.5V$ to 5.5V $C_{L} = 50 \text{ pF}$			
		Min	Max		
t _s (H)	Setup Time, HIGH	2.0		ns	Figure 7
t _s (L)	or LOW D _n to LE	2.0			
t _h (H)	Hold Time, HIGH	3.0		ns	Figure 7
t _h (L)	or LOW D _n to LE	3.0			
t _w (H)	Pulse Width,	6.0		ns	Figure 5
	LE HIGH				

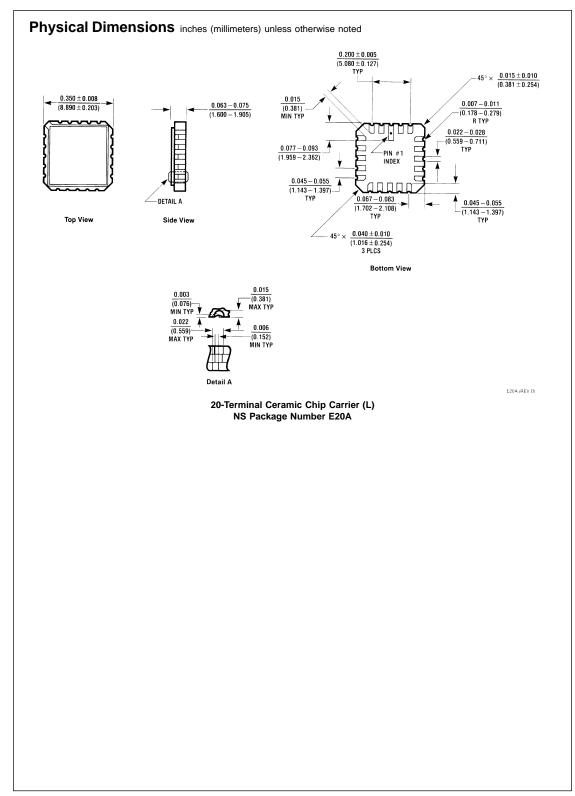
Capacitance

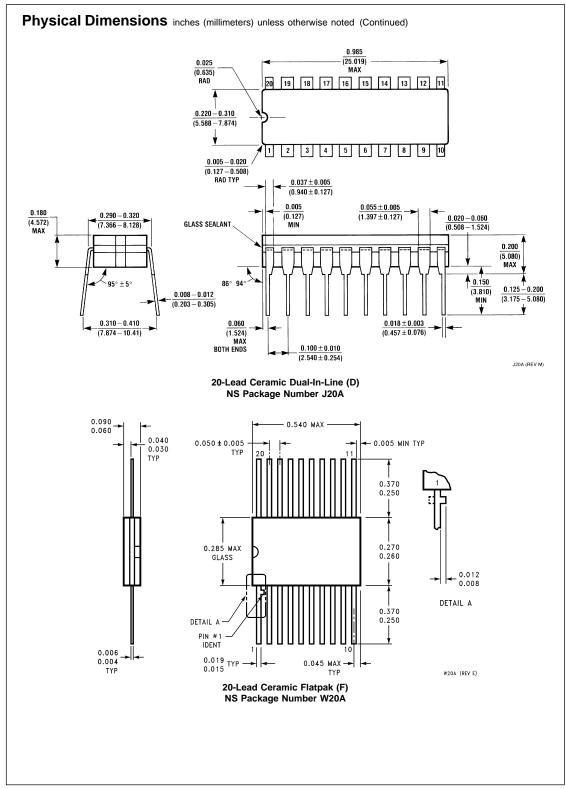
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Symbol	Parameter	Max	Units	Conditions
				(T _A = 25°C)
C _{IN}	Input Capacitance	10	pF	$V_{\rm CC} = 0V$
C _{OUT} (Note 3)	Output Capacitance	12	pF	$V_{\rm CC}$ = 5.0V

Note 3: C_{OUT} is measured at frequency f = 1 MHz, per MIL-STD-883B, Method 3012.







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